1 Package summary

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<th>Max</th>
<th>Unit</th>
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<td>40.2</td>
<td>mm</td>
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<td>40</td>
<td>40.2</td>
<td>mm</td>
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<td>seated height</td>
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<td>1.65</td>
<td>mm</td>
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<tr>
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<td>1</td>
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<tr>
<td>nominal pitch</td>
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<td>-</td>
<td>mm</td>
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<tr>
<td>actual quantity of termination</td>
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<td>-</td>
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</table>

IEC package outline code 144E
JEDEC package outline code MS-034
Mounted method type S (surface mount)
Issue date 17-03-2003
Manufacturer package code SOT605
2 Package outline

Figure 1. Package outline HBGA600 (SOT605-1)
3 Soldering

Footprint information for reflow soldering of HLBGA600 package

**Figure 2. Reflow soldering footprint for HBGA600 (SOT605-1)**
4 Legal information

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